

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1694	438/745	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/26 15:03
L2	256	438/747	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/26 15:04
L3	221	438/749	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/26 15:04
L4	252	438/750	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/26 15:04
L5	360	438/757	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/26 15:04
S2	1398	etch with SiN	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/26 15:03
S3	2	S2 with selectiv\$\$ with Aluminum adj Oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 11:49
S4	33	S2 with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 11:49
S5	0	S4 with solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 11:49
S6	942	HF adj10 solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 11:50

S7	19	S6 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 12:04
S8	0	S7 with SiN	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 11:51
S9	3	S7 with silicon adj nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 11:53
S10	579	HF with organic with solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 12:05
S11	9	S10 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 15:54
S12	217	Etch\$4 with (Si OR silicon) adj nitride with (Al OR aluminum) adj ox\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 15:57
S13	116	S12 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 16:06
S14	1	S13 with solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 15:57
S15	15	S13 and solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 15:58
S16	1	S14 and HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 15:58

S17	21	S13 and HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 15:59
S18	1	S13 with solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 16:06
S19	0	S13 with alcohol	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 16:06
S20	2726	(HF OR flori\$4) with solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 16:07
S21	47	S20 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 16:08
S22	4	S21 with (Al or Aluminun)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 16:08
S23	1883	selectivity with Aluminum	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:21
S24	253	S23 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 16:09
S25	0	S24 with solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 16:09
S26	114	ALON and HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 16:51

S27	11	S26 and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 16:56
S28	719	Hf with etch with nitride adj on adj oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 16:57
S29	0	Hf with etch with nitride adj on adj oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 16:57
S30	356	Hf with etch with nitride with oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 16:58
S31	1	S30 with solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 16:58
S32	28	S30 with select\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 17:02
S33	61	hf with organic with nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:06
S34	135233	wet adj etch nitride with oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:07
S35	3943	S34 with (HF OR flori\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:07
S36	797	wet adj etch with nitride with oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:08

S37	196	S35 and S36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:46
S38	5220	select\$4 with nitride with (AL OR AL2O3 OR aluminum adj oxide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:54
S39	560	S38 with (HF OR flour\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:51
S40	543	S38 with (HF OR flor\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:49
S41	1	S40 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:48
S42	0	S40 with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:48
S43	3	S39 with solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:52
S44	18	S39 with organic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:53
S45	6739	etch\$4 with nitride\$4 with oxide\$4 with selectiv\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:03
S46	904	S45 and organic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:57

S47	296	S46 and (flour\$4 or HF)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:57
S48	296	S47 and oxide\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 07:58
S49	11571	selectiv\$4 with (AlO OR aluminum)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:09
S50	275	S49 with (SiO2 or (silicon adj nitride))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:06
S51	6	S50 with (HF or flour\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:06
S52	905	selectiv\$4 with (aluminum adj oxide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:09
S53	5	S52 with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:16
S64	6810	etch with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:20
S69	12966	selectivity with oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:21
S70	2799	S69 with nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:22

S71	1333	S70 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:22
S72	38	S71 with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:25
S73	0	S72 with solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:24
S74	0	S72 with alchcohol	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:25
S75	2167	HF with solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/26 12:42
S76	45	S75 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:25
S77	4	S76 with nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:25
S78	211	HF with EG	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:28
S79	28	S78 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:29
S80	5	S79 with oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:29

S81	5	S80 with oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:31
S82	285	trench with etch with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:32
S83	2	S81 with nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:32
S84	2	S81 with nitrid\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:32
S85	132	via with etch with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:32
S86	3	S85 with nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:34
S87	80	nitrid\$4 with oxid\$4 with selectiv\$4 with HF with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:00
S88	1	S87 with solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:35
S89	0	S87 with oganic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:35
S90	1	S87 with organic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:42



S91	0	S87 with EG	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:35
S92	905	selectiv\$4 with aluminum adj oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:43
S93	5	S92 with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:48
S94	2213	HF and 49%	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:48
S95	19696	HF and 50%	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:49
S96	2450	HF and 50% adj wt	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 08:50
S97	7	HF adj 50% adj wt	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:08
S98	807	etch with nitride with aluminum	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:08
S99	11	S98 with hf	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:35
S10 0	188984	aluminum with oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:19

S10 1	58936	Al2O3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:19
S10 2	3021	Al2O3 with Aluminum	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:19
S10 3	9	S102 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:24
S10 4	15	"309940"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:23
S10 5	12342	etch with silicon adj nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:35
S10 6	323	S105 with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:36
S10 7	5	S106 with aluminum	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 09:36
S10 8	42	silicon with nitrid\$4 with selectiv\$4 with oxide with HF with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:02
S10 9	632	etch with nitride with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:04
S11 0	11	S109 with aluminum	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:03

S11 1	3893640	etch adj\$5 nitride with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:05
S11 2	13405	S111 with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:05
S11 3	465	S112 with aluminum	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:06
S11 4	6810	etch with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:06
S11 5	43	S114 with nitride adj etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:11
S11 6	2	"4269654".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:17
S11 7	226	metal adj oxid\$4 with make with transistor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:21
S11 8	16416	metal adj oxid\$4 with gate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:20
S11 9	89	metal adj oxid\$4 with make with gate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:23
S12 0	195	metal adj oxid\$4 adj gate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:28

S12 1	32	metal adj oxid\$4 with coat with dielectric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:32
S12 2	3231822	metal adj oxid\$4 with coat with n or p	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:29
S12 3	1917	metal adj oxid\$4 with coat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:29
S12 4	0	S123 with N+	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:29
S12 5	10909	silicon adj oxide with aluminum adj oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:32
S12 6	53	S125 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:51
S12 7	4800	dielectric adj oxides	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:51
S12 8	4920	dielectric adj oxid\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:52
S12 9	53	S128 with aluminum adj oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:51
S13 0	109	double adj dielectric with layer\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 11:00

S13 1	4	S130 with aluminum adj oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:53
S13 2	2	S130 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 10:59
S13 3	9	S130 with aluminum	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 11:02
S13 4	10	S130 with (aluminum OR "Al.sub. 2O.sub.3")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 11:02
S13 6	2	"4269654".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 11:21
S13 7	2	"6617190".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 15:41
S14 1	1	"20050061768"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 13:37
S14 6	19	Fluorinated adj surfactants aqueous adj acid adj etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 11:27
S14 7	1414	1% with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 14:21
S14 8	52	S147 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 13:38

S14 9	93	"L2" with nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 13:38
S15 0	1	S148 with nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 14:04
S15 1	4	S147 with solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 14:04
S15 2	2167	solvent with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 14:14
S15 3	49	S152 with clean	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 14:15
S15 4	0	S153 with 1%	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 14:15
S15 5	0	S153 with 5%	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 14:16
S15 6	0	S153 with 10%	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 14:16
S15 7	0	S153 with 15%	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 14:16
S15 8	2559	10% with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 14:21

S15 9	441	10% adj HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 14:21
S16 0	1	S159 with solvent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 14:21
S16 6	0	"60606604"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/09 07:49
S16 7	8	"6087273"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/09 07:51
S16 8	9	"5885903"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/09 07:51
S16 9	5978	silicon adj nitride with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:38
S17 0	866	(silicon adj nitride) same (isolation adj trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:38
S17 1	607	S170 and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:38
S17 2	838	S170 and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:38
S17 3	591	S171 and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:39

S17 4	0	S173 and almin\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:39
S17 5	0	S173 and Al2O3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:39
S17 6	470	S173 and Al	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:40
S17 7	2264593	S176 and Al adj\$3 oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:40
S17 8	470	S176 and (Al adj\$3 oxide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 12:42
S17 9	26	(nitride adj selectiv\$4 same metal) with oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:01
S18 0	0	(nitride adj selectiv\$4) with alimin\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:02
S18 1	390	(nitride adj selectiv\$4) with oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:51
S18 2	26	S181 with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:19
S18 3	1397	trench with metal adj oxid\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:06



S18 4	2	S182 with metal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:03
S18 5	30531	trench with ((metal adj oxid\$3) not adj\$3 semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:07
S18 6	27	S183 not semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:17
S18 7	12	S182 not plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:20
S18 8	3	S187 not slurry	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:23
S18 9	10246	etch with nitride with oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:23
S19 0	358	S189 with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:23
S19 1	5	S190 with alumin\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:48
S19 2	3254	wet adj etch with oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:50
S19 3	547	S192 with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:50

S19 4	0	S193 with over adj Almin\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:49
S19 5	0	S193 with (almin\$4 adj substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:49
S19 6	0	S193 and (almin\$4 adj substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:50
S19 7	1867	wet adj etch with nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:50
S19 8	815	wet adj etch with silicon adj nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:50
S19 9	73	S198 with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:51
S20 0	0	S199 with alumin\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 13:51
S20 1	15	S199 not plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:08
S20 2	529	hf with carboxylic adj acid	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:09
S20 3	1	S202 with silicon adj nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:10

S20 4	2	S202 with nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:11
S20 5	360	etch same nitride.ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:12
S20 6	19	S205 and HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:38
S20 7	1	double adj dielectric with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:38
S20 8	226	double adj dielectric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:39
S20 9	19	S208 and HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:38
S21 0	80588	silicon with (oxide and alumin\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:40
S21 1	6443	S210 and HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:40
S21 2	2923	S211 and dielectric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:41
S21 3	0	S212 and aluminun adj oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:41

S21 4	1936	S212 and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:41
S21 5	1391	S214 and etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:42
S21 6	856	S215 and wet	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:42
S21 7	0	(silicon adj oxide) with (aluminun adj oxide)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:43
S21 8	3329	(silicon adj oxide) with (alumina)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:43
S21 9	4594	(silicon adj oxide) same (alumina)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:43
S22 0	115	(silicon adj oxide) same (alumina).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:43
S22 1	2	S220 and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:44
S22 2	16118	barrier adj materials	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:44
S22 3	391	barrier adj material\$3 with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:44

S22 4	5	S223 with wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:47
S22 5	187	trench and nitride adj selectivity	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:47
S22 6	34	S225 and hF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 16:15
S22 7	5	etch with alumina with trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:53
S22 8	604	alumina with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:53
S22 9	48	S228 with stop adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 16:09
S23 0	0	S229 with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:54
S23 1	13	(nitride adj selectiv\$3) with alumin\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 16:16
S23 2	0	("2004/0147054").URPN.	USPAT	OR	ON	2005/05/18 16:18
S23 3	5362632	nitride adj\$3 over adj\$3 alumin\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 07:53
S23 4	14429	nitride with wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 07:54

S23 5	9663	S234 with silicon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 07:54
S23 6	788	S235 with aluminum	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 07:54
S23 7	457	S236 with silicon adj nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 07:54
S23 8	12	S237 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 07:58
S23 9	1391	S234 with etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 07:59
S24 0	33	S239 with HF	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 07:59
S24 1	0	S240 with alumin\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 07:59
S24 4	3423838	(etch\$4 remove\$4 roughen\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 11:00
S24 5	365684	((aluminum Al) adj oxide) AlOx "AlO.sub.x" "AlO.sub.x" AlOn "AlO. subn" "AlO.sub.n" alumina)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 11:01
S24 6	210701	(SiN (Silicon adj nitride) SiNx SixNx Si3N4 "Si.sub3.Nsub.4" "Si.sub3.N. sub.x" "Si.subx.N.sub.x")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 11:01

S24 7	181485	(HF (hydrogen adj fluoride) hydrofluoric (fluoric adj acid))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 11:02
S24 8	18	S244 with S245 with S246 with S247	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 11:02
S24 9	18211	S244 with S245	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 11:03
S25 0	417	S249 with S246	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 11:03
S25 1	18	S250 with S247	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 11:03
S25 2	17	S251 with (solvent glycol glycerol carboxylic acid polyol ethanol alcohol)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 11:05
S25 3	0	S251 same (solvent glycol glycerol carboxylic acid polyol ethanol alcohol).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 11:05
S25 4	20	(surface with (roughening or etch or removal)) with (silver adj (ion or nitride))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:43
S25 5	1	"4652465".PN.	USPAT; USOCR	OR	ON	2005/05/19 12:29
S25 6	1	"0595944".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 12:40
S25 7	0	09/0595944	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 12:40

S25 8	0	US20040099637	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 12:40
S25 9	0	US20040099637	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 12:40
S26 0	0	10/0099637	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 12:41
S26 1	0	10/99637	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 12:41
S26 2	2	2000US-0595944	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 13:44
S26 3	1	10/421293	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 14:00
S26 4	0	09/595944	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 14:00
S26 5	0	09/595944	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 14:01
S26 6	0	09/595944.ap.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 14:01
S26 7	2	"09595944"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 14:38



S26 8	745	(halide adj ion) with (silver adj ion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:43
S26 9	8	S268 with (etch\$4 remove\$4 roughten\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:45
S27 0	0	S269 with crystal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:45
S27 1	745	(halide adj ion) with (silver adj ion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:48
S27 2	251	S271 with crystal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:48
S27 3	39	roughten\$4 etch with HF with silver with halide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:56
S27 4	2117	surface with treat\$5 with (halide or (halide adj ion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:59
S27 5	985	S274 with silver	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:57
S27 6	985	S275 with (silver Ag)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:58
S27 7	1029	S274 with (silver Ag)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:58

S27 8	1	S277 with azole	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:58
S27 9	447724	surface with treat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:59
S28 0	487478	surface with (treat\$5 roughen44 etch)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:59
S28 1	1283605	copper Cu (copper adj clad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:01
S28 2	5236309	azole silver (silver adj nitride) Au	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:02
S28 3	597593	halide chlorine bromine flourine iodine	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:03
S28 4	854255	ion	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:03
S28 5	41	S280 with S281 with S283 with S284	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:06
S28 6	5	S285 with ppm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:07
S28 7	13911	glycolic adj acid and ((ethylene adj glycol) or glycerol)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/26 09:36

S28 8	2074	glycolic adj acid same ((ethylene adj glycol) or glycerol)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/26 09:37
S28 9	200	(glycolic adj acid same ((ethylene adj glycol) or glycerol)).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/26 09:37
S29 0	2	"4269654".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/26 13:01
S29 1	9	ethanol same (ethylene adj glycol) same etchant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/26 13:09
S29 2	7	"1,160,945".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/26 13:10
S29 3	3528739	GB "1,160,945"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/26 13:10
S29 4	7	("3293148"   "3481877"   "3810797"   "4477290").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:14
S29 5	12159	(Chelat\$3 ajd agent\$3) same ethanol same alumi\$3	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:15
S29 6	10	(Chelat\$3 ajd agent\$3) same ethanol same alumi\$3.ab.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 14:00
S29 7	10	((Chelat\$3 ajd agent\$3) same ethanol same alumi\$3).ab.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:17
S29 8	1098012	(Chelat\$3 ajd agent\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:17
S29 9	376996	ethanol	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:18
S30 0	909269	alumi\$3	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:18

S30 1	12159	S298 same S299 same S300	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:18
S30 2	10	(S298 same S299 same S300).ab.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 14:07
S30 3	50	chealating	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:19
S30 4	56726	chelating	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:19
S30 5	0	(S304 same S299 same S300).ab.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:19
S30 6	10	(S304 same S299).ab.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:59
S30 7	0	great adj britain same "1160945"	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:35
S30 8	0	"1160945" near anderson	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:35
S30 9	0	"1160945" same Anderson	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:36
S31 0	2	"1160945" and Anderson	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:37
S31 1	0	"1160945" and (United adj Kingdom)	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:46
S31 2	0	"1160945-pal.#-\$did."	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:46
S31 3	0	"1160945 pal.#-\$did."	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 13:46
S31 4	16980	chelate and ethanol	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 14:00
S31 5	4854	Chelat\$3 same ethanol	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 14:01
S31 6	17	(Chelat\$3 same ethanol).ab.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 14:01

S31 7	3045	sheetz	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 14:07
S31 8	4	sheetz same aluminum	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/26 14:07